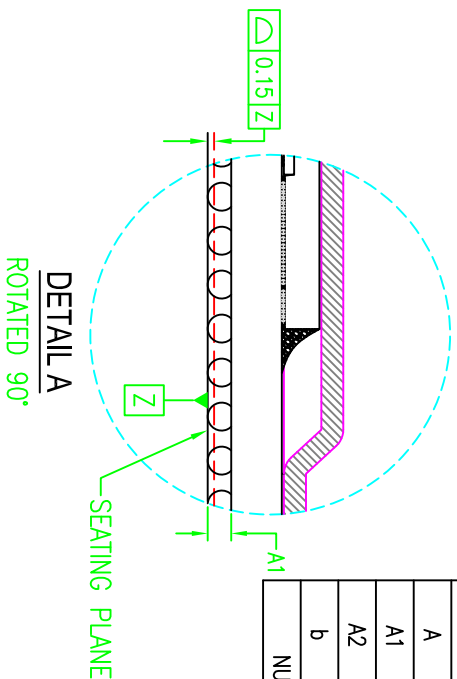


DIMENSION	MINIMUM	NOMINAL	MAXIMUM
A	2.061	2.277	2.492
A1	0.257	0.307	0.357
A2	1.804	1.970	2.135
b	0.350	0.400	0.450
NUMBER OF BALLS 684			



- NOTES:
1. ALL DIMENSIONS AND TOLERANCE CONFORM TO ASME Y14.5M-1994.
  2. TERMINAL POSITIONS DESIGNATION PER JEDEC 95-1, SPP-010.
  3. CORNER DETAILS PER STATS ChipPAC OPTION.
  4. REFLOW BALL DIAMETER.
  5. COMPLIANT TO JEDEC REGISTERED OUTLINE MS-034, NO EXACT VARIATION AND WITH EXCEPTION TO DIM 'A'.
  6. RAW SOLDER BALL SIZE DURING ASSEMBLY IS  $\phi 0.400\text{MM}$ .

---	A	Initial Release	16 OCT 17	--	--	--	--
ECN	REV.	DESCRIPTION	DATE	DESIGNED	DRAWN	CHECKED	APPROVED
GJCET		TITLE : PACKAGE OUTLINE					
STATS ChipPAC		fcBGA-H, 19.0 X 19.0mm, 0.65 PITCH					
A-00000000		684LD					
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS. TOLERANCES ARE:		PROJECTION		DRAWING NUMBER:			
DECIMALS X.XX ±0.05 X.XXX ±0.050		SCALES		REV.			
ANGLES ±1°		SIZE A4		SHEET			
NONE		NONE		1 OF 1			